

**Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	Conditions
Peak Pulse Power Dissipation	P <sub>PP</sub>	300	W	8/20μs, per Figure 3
Peak Pulse Current	I <sub>PP</sub>	12	A	8/20μs, per Figure 3
ESD Protection – Contact Discharge	V <sub>ESD_Contact</sub>	±30	kV	IEC 61000-4-2 Standard
ESD Protection – Air Discharge	V <sub>ESD_Air</sub>	±30	kV	IEC 61000-4-2 Standard

**Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Package Power Dissipation (Note 5)	P <sub>D</sub>	250	mW
Thermal Resistance, Junction to Ambient (Note 5)	R <sub>θJA</sub>	500	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-65 to +150	°C

**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Conditions
Reverse Working Voltage	V <sub>RWM</sub>	—	—	15.0	V	—
Reverse Current (Note 6)	I <sub>R</sub>	—	—	100	nA	V <sub>R</sub> = V <sub>RWM</sub> = 15.0V
Reverse Breakdown Voltage	V <sub>BR</sub>	16	—	19	V	I <sub>R</sub> = 1mA
Reverse Clamping Voltage	V <sub>CL</sub>	—	—	22	V	I <sub>PP</sub> = 5A, t <sub>p</sub> = 8/20μs
		—	—	27		I <sub>PP</sub> = 12A, t <sub>p</sub> = 8/20μs
Capacitance	C <sub>T</sub>	—	70	90	pF	V <sub>R</sub> = 0V, f = 1MHz

Notes: 5. Device mounted on FR-4 PCB pad layout (2oz copper) as shown on Diodes Incorporated's suggested pad layout, which can be found on our website at <http://www.diodes.com/package-outlines.html>.  
 6. Short duration pulse test used to minimize self-heating effect.

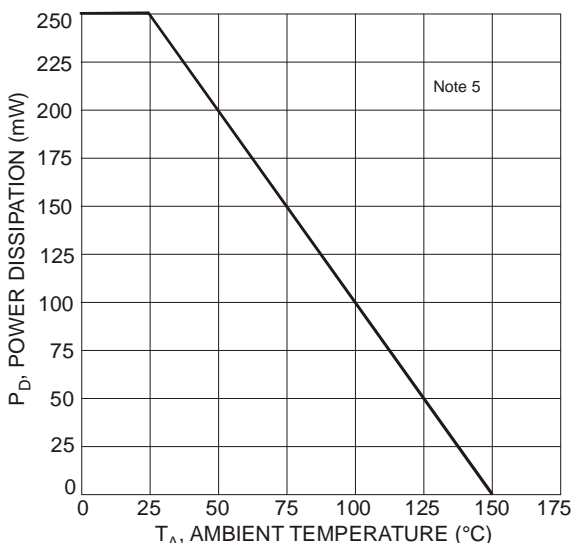


Figure 1 Power Derating Curve

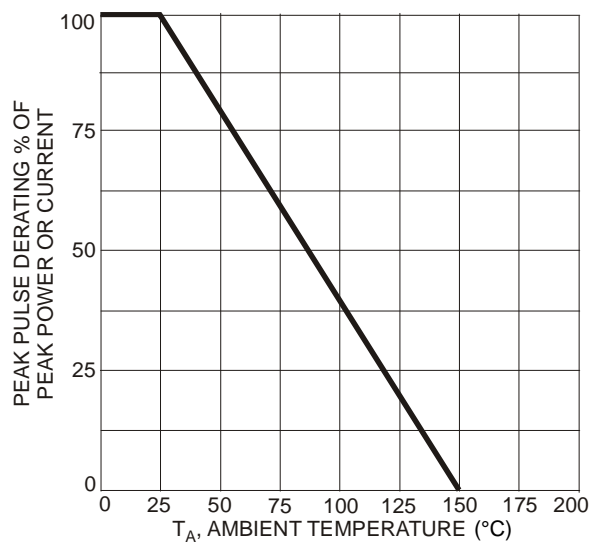


Figure 2 Pulse Derating Curve

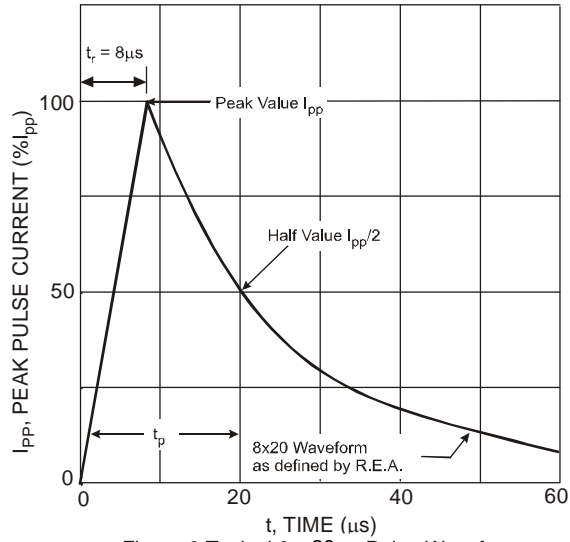


Figure 3 Typical 8 x 20µs Pulse Waveform

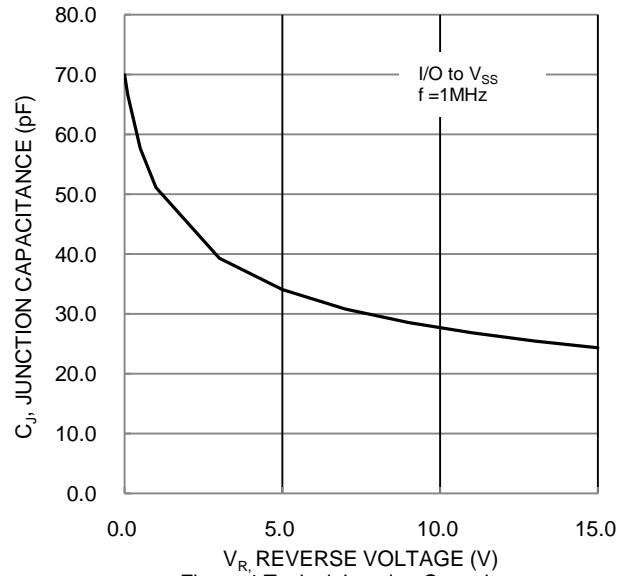


Figure 4 Typical Junction Capacitance

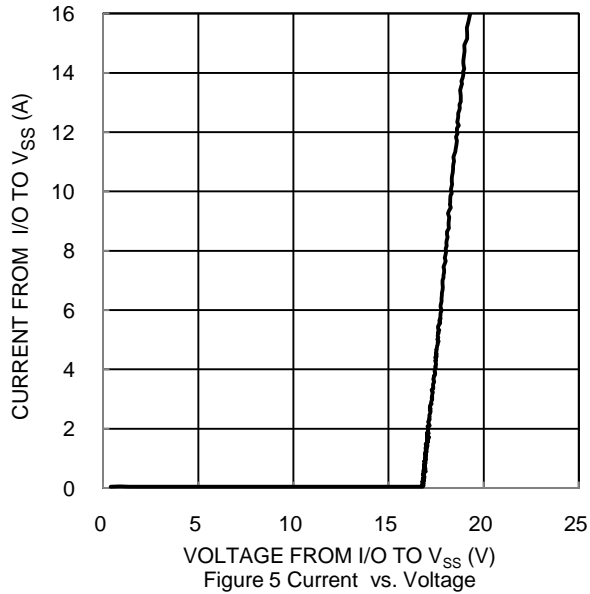
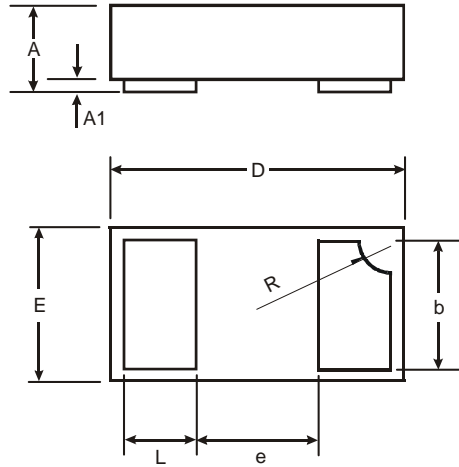


Figure 5 Current vs. Voltage

## Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**X1-DFN1006-2**

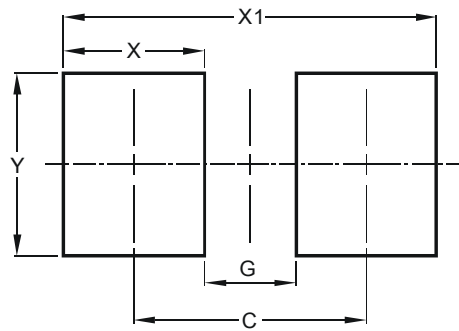


X1-DFN1006-2			
Dim	Min	Max	Typ
A	0.47	0.53	0.50
A1	0	0.05	0.03
b	0.45	0.55	0.50
D	0.95	1.075	1.00
E	0.55	0.675	0.60
e	-	-	0.40
L	0.20	0.30	0.25
R	0.05	0.15	0.10
All Dimensions in mm			

## Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**X1-DFN1006-2**



Dimensions	Value (in mm)
C	0.70
G	0.30
X	0.40
X1	1.10
Y	0.70

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